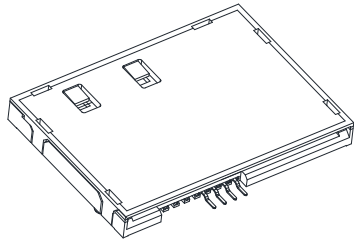




**ALTERNATIVE  
COMPONENT  
SOURCE**

a Major League Electronics Company

2533 Centennial Blvd. Jeffersonville, Indiana, USA 47130



**EMV Compliant**

## TECHNICAL CHARACTERISTICS

### 1. General Characteristics

Dimension: 55.50L x 40.00W x 5.80H mm  
 Weight: Approx. 12.55 g  
 Contact principle: Landing technology  
 Operating position: Shaft up / Down / Horizontal  
 Mounting System: DIP or SMT Type (with post)  
 Durability: 500,000 cycles min.

### 2. Mechanical Characteristics

Insulation material: Thermoplastic, UL 94V-0  
 RoHS Directive 2011/65/EU Compliant

### 3. Electrical Characteristics

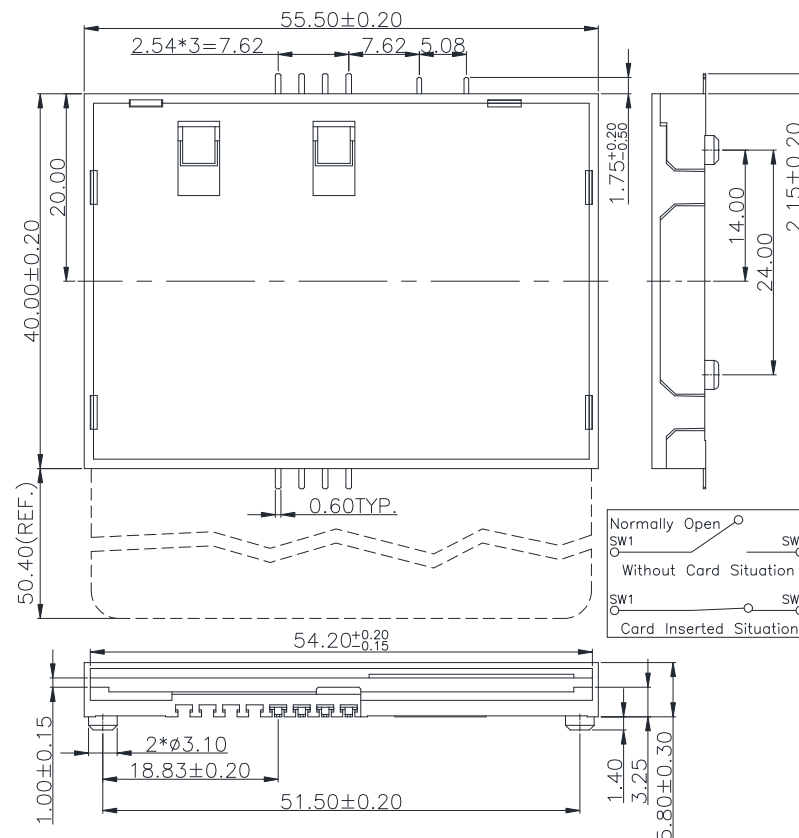
Number of contacts: 8 pins  
 Contact resistance: 50 mΩ typical, 100 mΩ max.  
 Insulation resistance: >1000 MΩ / 500 VDC  
 Switch type: Sealed  
 Operation: Normally Open

### 4. Solderability

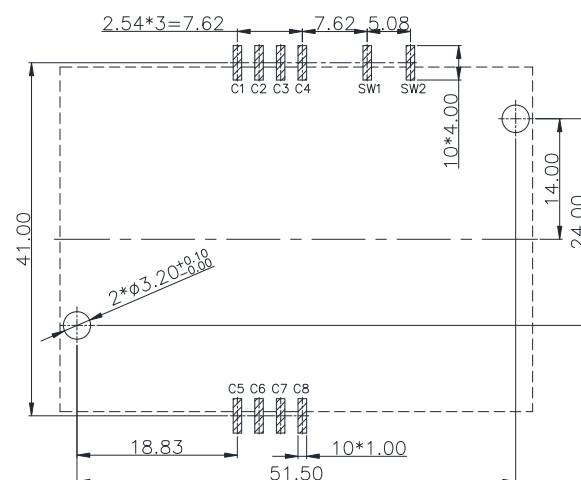
Wave: Not applicable  
 IR reflow: Not applicable  
 Manual soldering: 360C, 3 sec. Max.

### 5. Environmental Characteristics

Operating temperature: - 40C ~ + 85C  
 Operating humidity: 10 % ~ 95 % RH  
 Storage temperature: - 40C ~ + 85C  
 Storage humidity: 10 % ~ 95 % RH



Unit: mm; Tolerances: 0.15 mm  
**Mechanical outline dimension**



Unit: mm; Tolerances: 0.05 mm  
**Reference dimension for PCB layout**

**Smart Card Acceptor**

**Model No.: ICA-705 SMT**

**Revision: 1.6**

**Date: MAY 01, 2014**

Note:

1. Coplanarity of solder pins 0.10mm max.
2. Recommended thickness of solder paste > 0.15mm.